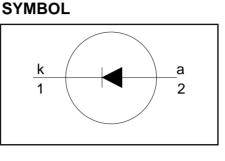
### Rectifier diodes fast, soft-recovery

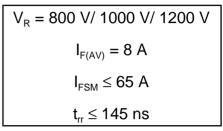
### BY329F, BY329X series

### FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- High thermal cycling performance
- Isolated mounting tab



### QUICK REFERENCE DATA



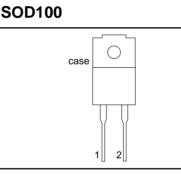
### **GENERAL DESCRIPTION**

Glass-passivated double diffused rectifier diodes featuring low forward voltage drop, fast reverse recovery and soft recovery characteristic. The devices are intended for use in TV receivers, monitors and switched mode power supplies.

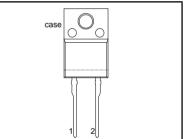
The BY329F series is supplied in the conventional leaded SOD100 package. The BY329X series is supplied in the conventional leaded SOD113 package.

#### PINNING

# PINDESCRIPTION1cathode2anodetabisolated







### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	I. MAX.			UNIT
V <sub>RSM</sub>	Peak non-repetitive reverse voltage	BY329F / BY329X	-	<b>-800</b> 800	<b>-1000</b> 1000	<b>-1200</b> 1200	V
V <sub>rrm</sub> V <sub>rwm</sub>	Peak repetitive reverse voltage Crest working reverse voltage		-	800 600	1000 800	1200 1000	V V
I <sub>F(AV)</sub>	Average forward current <sup>1</sup>	square wave; $\delta = 0.5$ ; T <sub>hs</sub> $\leq 83$ °C sinusoidal; a = 1.57; T <sub>hs</sub> $\leq 90$ °C	-		8 7		A A
I <sub>F(RMS)</sub> I <sub>FRM</sub>	RMS forward current Peak repetitive forward current	$t = 25 \ \mu s; \ \delta = 0.5;$ $T_{hs} \le 83 \ ^{\circ}C$	-		11 16		A A
I <sub>FSM</sub>	Peak non-repetitive forward current.	t = 10 ms t = 8.3 ms sinusoidal; T <sub>i</sub> = 150 °C prior to surge; with reapplied	-		65 71		A A
$\begin{matrix} I^2 t \\ T_{stg} \\ T_j \end{matrix}$	I <sup>2</sup> t for fusing Storage temperature Operating junction temperature	$V_{\text{RWM(max)}}$ t = 10 ms	- -40 -		28 150 150		A²s °C °C

1. Neglecting switching and reverse current losses.

### Rectifier diodes fast, soft-recovery

### BY329F, BY329X series

### **ISOLATION LIMITING VALUE & CHARACTERISTIC**

 $T_{hs} = 25$  °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	Peak isolation voltage from both terminals to external heatsink	SOD100 package; R.H. $\leq$ 65%; clean and dustfree	-	-	1500	V
V <sub>isol</sub>	R.M.S. isolation voltage from both terminals to external heatsink	SOD113 package; f = 50-60 Hz; sinusoidal waveform; R.H. $\leq$ 65%; clean and dustfree	-	-	2500	V
C <sub>isol</sub>	Capacitance from pin 1 to external heatsink	f = 1 MHz	-	10	-	pF

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-hs</sub> R <sub>th j-a</sub>	heatsink	with heatsink compound without heatsink compound in free air.	- -	- - 55	4.8 5.9 -	K/W K/W K/W

### STATIC CHARACTERISTICS

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 20 A	-	1.5	1.85	V
I <sub>R</sub>	Reverse current	V <sub>R</sub> = V <sub>RWM</sub> ; T <sub>i</sub> = 125 °C		0.1	1.0	mA

### DYNAMIC CHARACTERISTICS

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t <sub>rr</sub> Q <sub>s</sub> dI <sub>R</sub> /dt	Reverse recovery charge	$ \begin{array}{l} I_{F}=1 \; A; \; V_{R} \geq 30 \; V; \; \text{-dI}_{F}/\text{dt} = 50 \; \text{A}/\mu s \\ I_{F}=2 \; A; \; V_{R} \geq 30 \; V; \; \text{-dI}_{F}/\text{dt} = 20 \; \text{A}/\mu s \\ I_{F}=2 \; A; \; \text{-dI}_{F}/\text{dt} = 20 \; \text{A}/\mu s \end{array} $	- - -	125 0.5 50	145 0.7 60	ns μC A/μs

BY329F, BY329X series

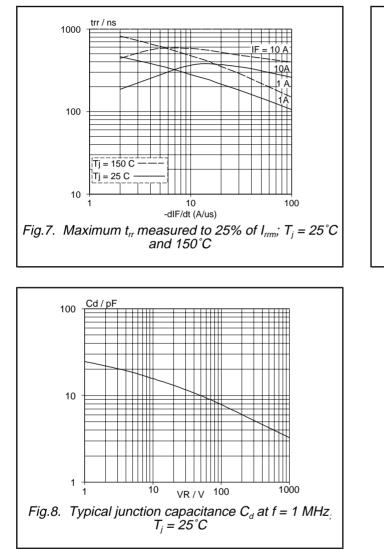
### Rectifier diodes fast, soft-recovery

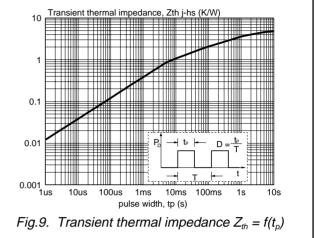
#### dl F IFS (RMS) / A 100 $I_{F}$ 90 dt 80 70 IFSN trr 110 60 time 50 40 30 Qs 100% 25% 20 10 I R l rrm 0 10ms 0.1s . 1ms 1s 10s tp/s Fig.4. Maximum non-repetitive rms forward current. $I_F = f(t_p)$ ; sinusoidal current waveform; $T_j = 150^{\circ}C$ prior to surge with reapplied $V_{RWM}$ . Fig.1. Definition of $t_{rr}$ , $Q_s$ and $I_{rrm}$ Ths(max) / C PF/W IF / A 30 20 54 D = 1.0 $V_0 = 1.25$ Ti = 150 C0.03 O = 25 C Tj 15 78 'n 20 0 102 10 0.1 10 <u>t</u>p tρ D = 126 5 ma 150 0 0 1.5 6 IF(AV) / A ò 0.5 Ó 8 10 12 1 4 2 . VF/V Fig.2. Maximum forward dissipation, $P_F = f(I_{F(AV)})$ ; square wave current waveform; parameter D = dutycycle = $t_p/T$ . Fig.5. Typical and maximum forward characteristic; $I_F = f(V_F)$ ; parameter $T_i$ PF/W Ths(max) / C Qs / uC 10 15 78 Tj = 150 C Vo = 1.25 V Tj = 25 C a = 1.57 Rs = 0.03 Ohm 2.2 10 A 10 102 2.8 1 5 126 0 150 0.1 10 0 2 4 6 8 100 IF(AV) / A -dIF/dt (A/us) Fig.3. Maximum forward dissipation, $P_F = f(I_{F(AV)})$ ; sinusoidal current waveform; parameter a = formfactor = $I_{F(RMS)}/I_{F(AV)}$ . Fig.6. Maximum $Q_s$ at $T_i = 25^{\circ}C$ and $150^{\circ}C$

Product specification

## Rectifier diodes fast, soft-recovery

### BY329F, BY329X series

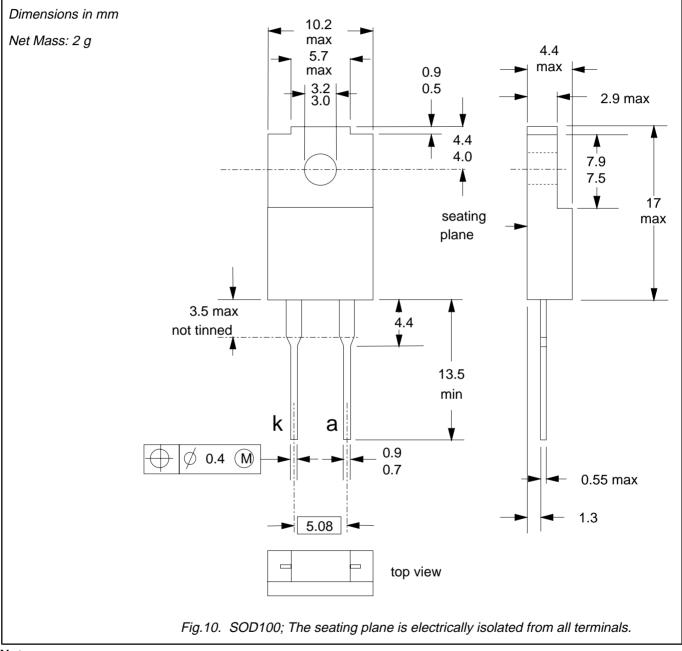




### **Rectifier diodes** fast, soft-recovery

### BY329F, BY329X series

### **MECHANICAL DATA**



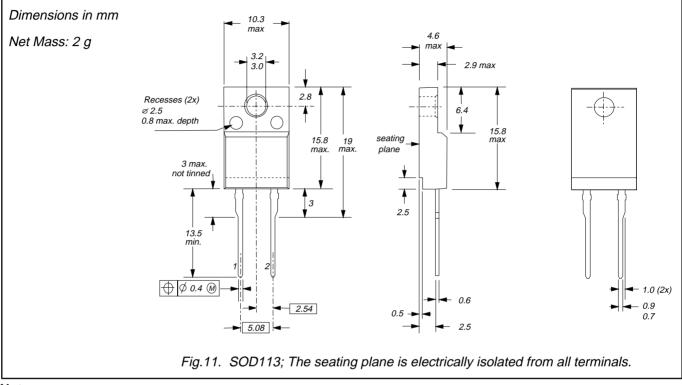
#### Notes

Refer to mounting instructions for F-pack envelopes.
Epoxy meets UL94 V0 at 1/8".

### **Rectifier diodes** fast, soft-recovery

### BY329F, BY329X series

### **MECHANICAL DATA**



#### Notes

Refer to mounting instructions for F-pack envelopes.
Epoxy meets UL94 V0 at 1/8".

### Rectifier diodes fast, soft-recovery

### BY329F, BY329X series

### DEFINITIONS

Data sheet status					
Objective specification	Dbjective specification This data sheet contains target or goal specifications for product development.				
Preliminary specification	reliminary specification This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	on This data sheet contains final product specifications.				
Limiting values					
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					
Where application information is given, it is advisory and does not form part of the specification.					
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